● General Description

The AGM01P15E combines advanced trench MOSFET technology with a low resistance package to provide extremely low $R_{DS(ON)}$

This device is ideal for load switch and battery protection applications.

● Features

- Advance high cell density Trench technology
- Low $R_{DS(ON)}$ to minimize conductive loss
- Low Gate Charge for fast switching
- Low Thermal resistance
- 100% DVDS tested

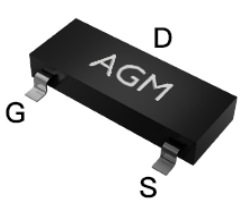
● Application

- MB/VGA Vcore
- SMPS 2nd Synchronous Rectifier
- POL application
- BLDC Motor driver

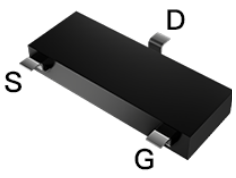
Product Summary

BVDSS	RDSON	ID
-100V	270mΩ	-4.3A

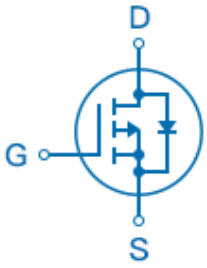
SOT23-3 Pin Configuration



Top View



Bottom View



Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
01P15E	AGM01P15E	SOT23-3	178mm	8mm	3000

Table 1. Absolute Maximum Ratings (TA=25℃)

Symbol	Parameter	Value	Unit
VDS	Drain-Source Voltage (VGS=0V)	-100	V
VGS	Gate-Source Voltage (VDS=0V)	±20	V
ID	Drain Current-Continuous(Tc=25℃) **(Note 1)**	-4.3	A
	Drain Current-Continuous(Tc=100℃)	-2.9	A
IDM (pluse)	Drain Current-Pulsed **(Note 2)**	-17.2	A
PD	Maximum Power Dissipation(Tc=25℃)	1.25	w
	Maximum Power Dissipation(Tc=100℃)	1.0	w
EAS	Avalanche energy **(Note 3)**	30	mJ
TJ,TSTG	Operating Junction and Storage Temperature Range	-55 To 150	℃

Table 2. Thermal Characteristic

Symbol	Parameter	Typ	Max	Unit
RθJA	Thermal Resistance Junction-ambient (Steady State)[1]	---	100	℃/W

Table 3. Electrical Characteristics (TJ=25℃unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
On/Off States						
BV_{DSS}	Drain-Source Breakdown Voltage	VGS=0V ID=-250μA	-100	--	--	V
IDSS	Zero Gate Voltage Drain Current	VDS=-100V,VGS=0V	--	--	-1	μA
IGSS	Gate-Body Leakage Current	VGS=±20V,VDS=0V	--	--	±100	nA
$V_{GS(th)}$	Gate Threshold Voltage	VDS=VGS,ID=-250μA	-1.2	-1.6	-2.2	V
gFS	Forward Transconductance	VDS=-5V,ID=-2A	--	7.0	--	S
RDS(on)	Drain-Source On-State Resistance	VGS=-10V, ID=-4A	--	270	340	mΩ
		VGS=-4.5V, ID=-2A	--	280	345	mΩ
Dynamic Characteristics						
Ciss	Input Capacitance	VDS=-50V,VGS=0V, F=1MHZ	--	1199	--	pF
Coss	Output Capacitance		--	34	--	pF
Crss	Reverse Transfer Capacitance		--	28	--	pF
Rg	Gate resistance	VGS=0V, VDS=0V,f=1.0MHz	--	5.2	--	Ω
Switching Times						
td(on)	Turn-on Delay Time	VGS=-10V,VDS=-50V, RL=3Ω,RGEN=3Ω	--	13.5	--	nS
tr	Turn-on Rise Time		--	4.0	--	nS
td(off)	Turn-Off Delay Time		--	42	--	nS
tf	Turn-Off Fall Time		--	6.5	--	nS
Qg	Total Gate Charge	VGS=-10V, VDS=-50V, ID=-3A	--	19.5	--	nC
Qgs	Gate-Source Charge		--	6.0	--	nC
Qgd	Gate-Drain Charge		--	4.1	--	nC
Source-Drain Diode Characteristics						
ISD	Source-Drain Current(Body Diode)		--	--	-4.3	A
VSD	Forward on Voltage	VGS=0V,IS=-3A	--	--	-1.2	V
trr	Reverse Recovery Time	Isd=-3A , dI/dt=100A/μs , TJ=25℃	--	43	--	ns
Qrr	Reverse Recovery Charge		--	84	--	nc

Notes 1.The maximum current rating is package limited.

Notes 2.Repetitive Rating: Pulse width limited by maximum junction temperature

Notes 3.EAS condition: TJ=25℃

Typical Electrical And Thermal Characteristics (Curves)

Figure 1. Output Characteristics

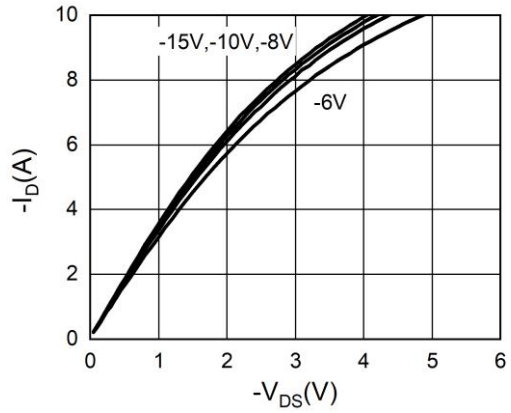


Figure 2. Transfer Characteristics

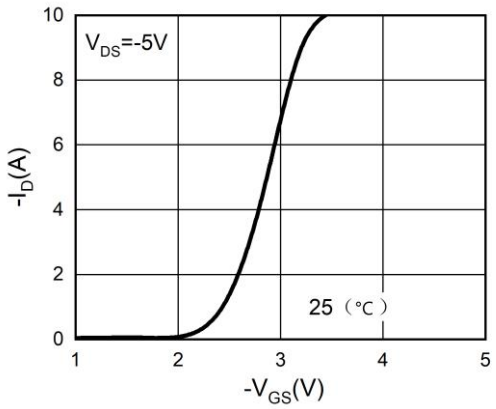


Figure 3. Power Dissipation

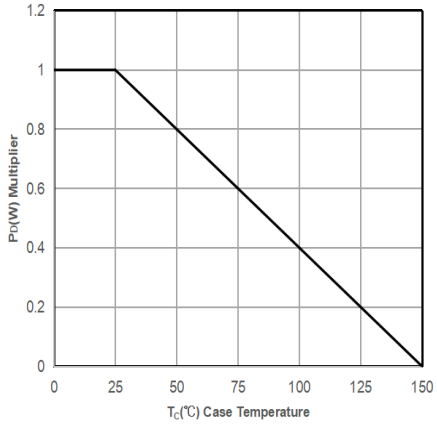


Figure 4. Drain Current

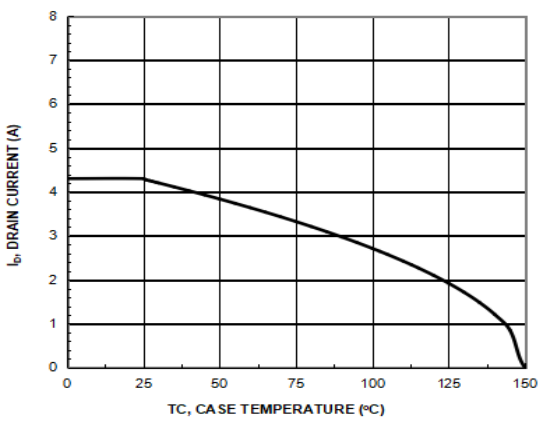


Figure 5. BV_{DSS} vs Junction Temperature

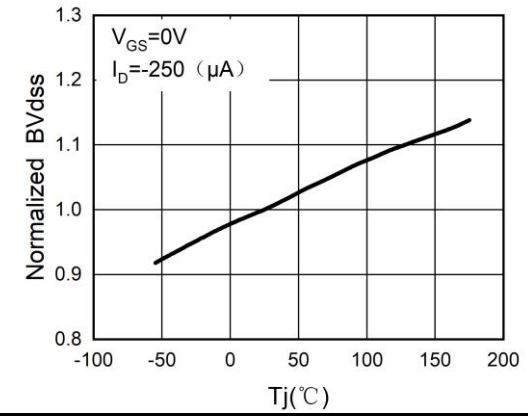
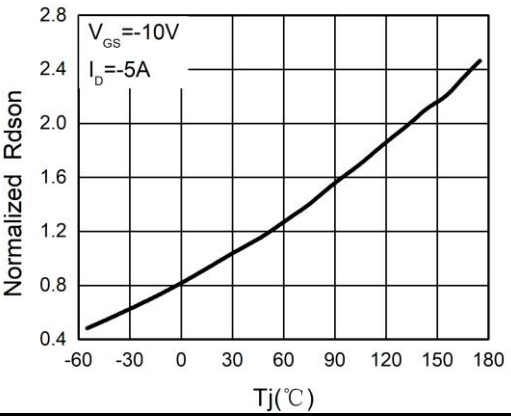


Figure 6. $R_{DS(ON)}$ vs Junction Temperature



Typical Electrical And Thermal Characteristics (Curves)

Figure 7. Gate Charge Waveforms

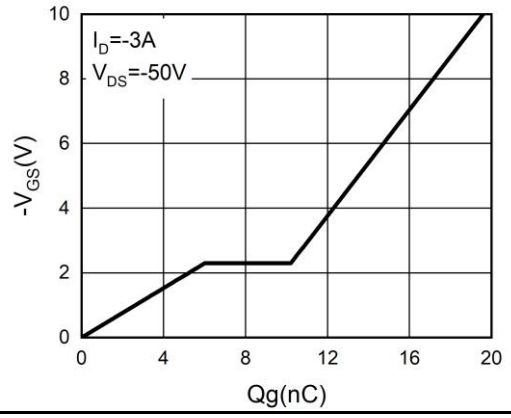


Figure 8. Capacitance

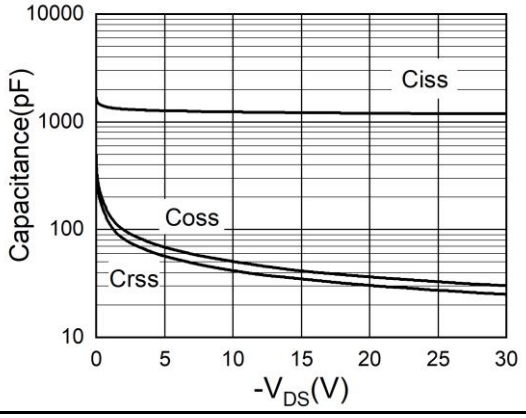


Figure 9. Body-Diode Characteristics

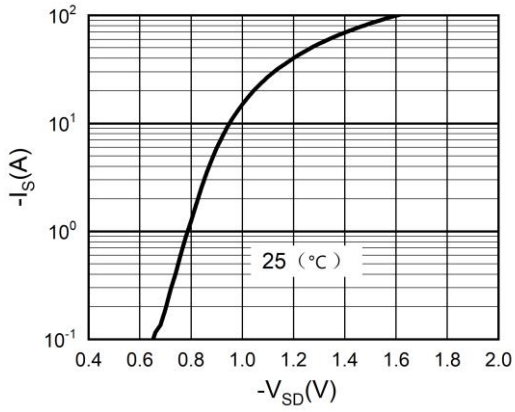
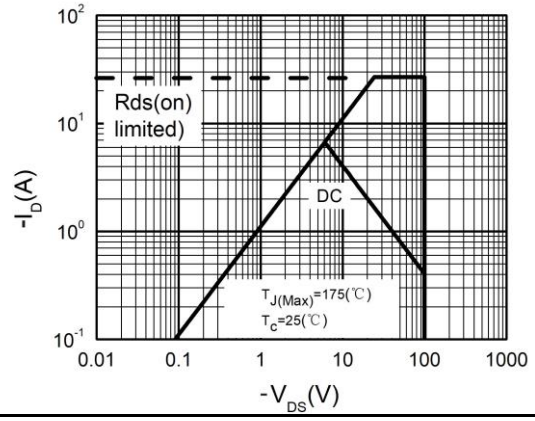
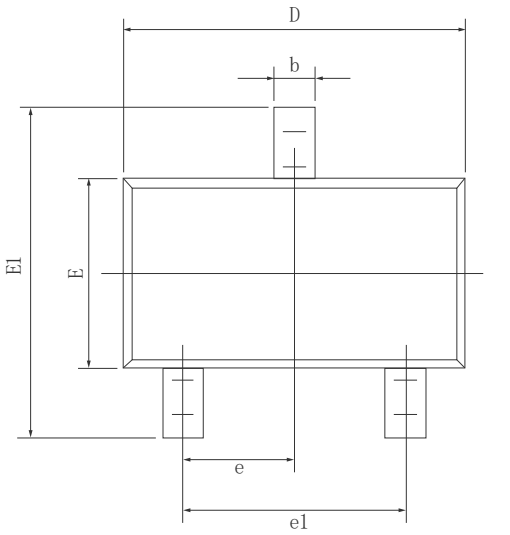
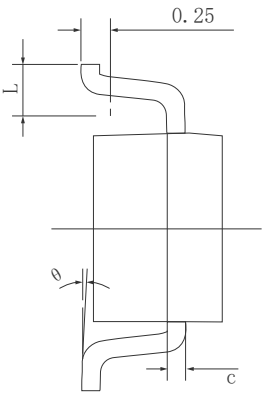


Figure 10. Maximum Safe Operating Area

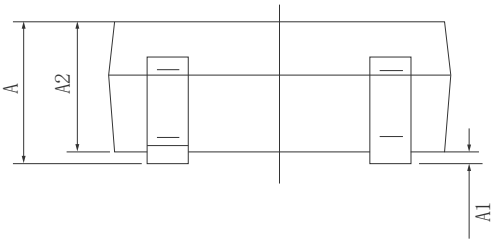


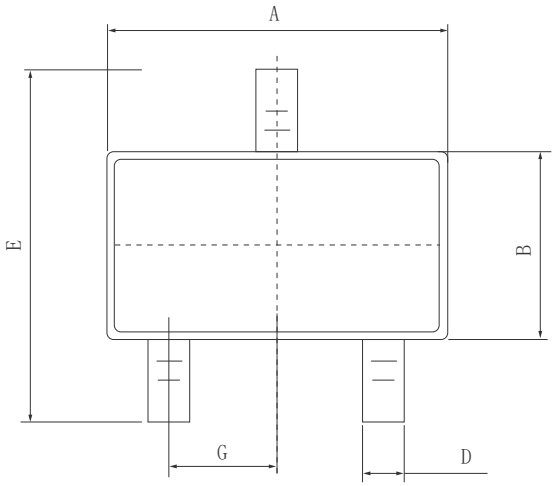
●Dimensions（SOT23-3）

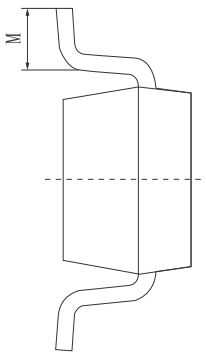




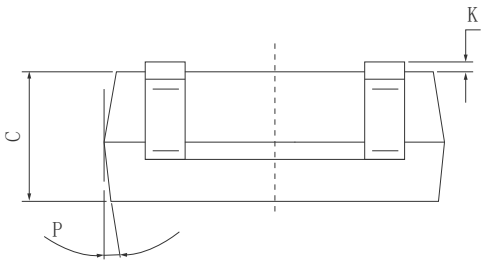
SYMBOL	MILLIMETER		
	MIN	NOM	MAX
A	—	—	1.25
A1	0.03	—	0.10
A2	1.05	1.10	1.15
b	0.30	0.35	0.40
c	0.13	—	0.17
D	2.87	2.92	2.97
E	1.55	1.60	1.65
E1	2.70	2.85	3.00
e	0.95 BSC.		
e1	1.80	—	2.00
L	0.35	0.45	0.55
θ	0°	—	8°





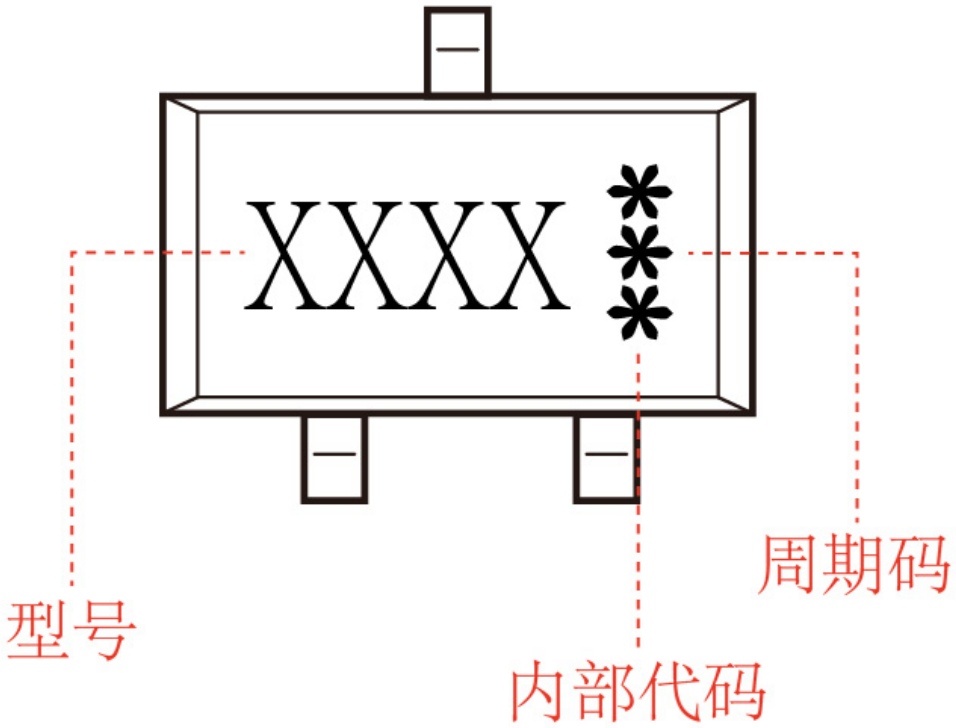


DIM	MILLIMETERS
A	2.82~3.02
B	1.60±0.10
C	1.10±0.05
D	0.40±0.10
E	2.65~2.95
G	0.95typ
K	0.00~0.10
M	0.20MIN
P	9±2°



SOT23-3

Marking Instructions:



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